(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property Organization International Office		
(43) International Publication Date 6 June 2002 (06.06.2002)	PCT	(10) International Publication Number **WO 02/45163 A2**

(51) International Patent Classification[7]: H01L 23/13 21/60

(21) International Application Number: PCT/DE01/04489

(22) International Filing Date: 29 November 2001 (29.11.2001)

(25) Language in which the international application was originally filed: German

(26) Language in which the international application is published: German

(30) Priority Data:
100 59 178.7 29 November 2000 (29.11.2000) DE

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(81) Designated States (national): CN, JP, KR, SG, US.

(84) Designated States (regional): European patent (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE, TR).

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(54) **Title:** METHOD FOR PRODUCING SEMICONDUCTOR MODULES AND A MODULE PRODUCED ACCORDING TO SAID METHOD

(Figure)



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(57) **Abstract:** According to the invention, the connection side of an undivided semiconductor wafer (1) is directly connected to a thermoplastic film (2), whose thermal expansion coefficient is approximately as low as that of the semiconductor material. Protuberances (21) are molded onto the exposed underside of the film (2) by a hot embossing process, said protuberances acting as elastic external connections (25) and being connected in a conductive manner to internal connections (24) or to the wafer terminal elements(11) via passages (22). Individual semiconductor modules or packages that can be contacted on a printed circuit board by means of the plastic protuberances (21) are produced by dividing the finished contacted wafer. Said method allows semiconductor chips to be contacted on an intermediate support and the intermediate support to be contacted on a printed circuit board in a simple manner, ensuring a temperature-resistant connection between the semiconductor and the printed circuit board, without additional compensatory materials.

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